

	<b>SEMITOP</b> <sup>®</sup>	2
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## **Bridge Rectifier**

#### SK 55 D

**Target Data** 

### **Features**

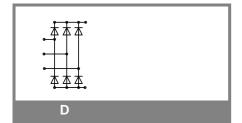
- · Compact design
- · One screw mounting
- Heat transfer and insulation through direct copper bonded aluminium oxide ceramic (DCB
- Up to 1600V reverse voltage
- High surge currents
- · Glass passived diodes chips
- UL recognized, file no. E 63 532

## **Typical Applications**

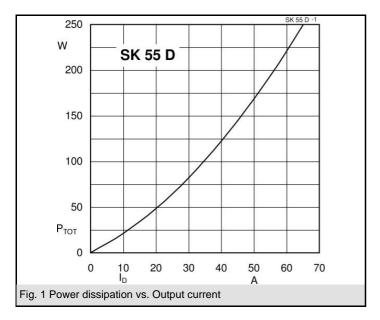
- Input rectifier for power supplies
- Rectifier

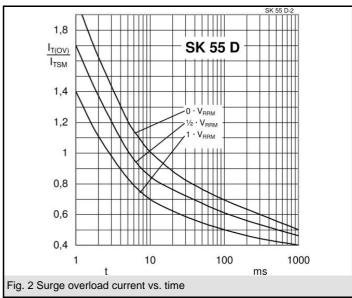
V <sub>RSM</sub>	$V_{RRM}, V_{DRM}$	I <sub>D</sub> = 55 A (full conduction)
V	V	(T <sub>s</sub> = 80 °C)
800	800	SK 55 D 08
1200	1200	SK 55 D 12
1600	1600	SK 55 D 16

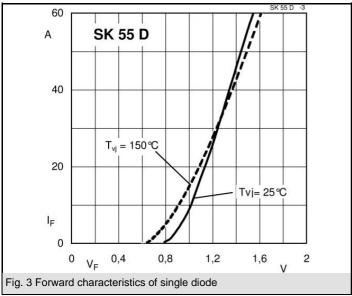
Symbol	Conditions	Values	Units
I <sub>D</sub>	T <sub>s</sub> = 80 °C	55	А
$I_D$	T <sub>s</sub> = 100 °C	45	Α
I <sub>FSM</sub>	T <sub>vj</sub> = 25 °C; 10 ms	370	А
	T <sub>vi</sub> = 150 °C; 10 ms	270	Α
i²t	$T_{vj} = 25 ^{\circ}\text{C}; 8,310 \text{ms}$	685	A²s
	T <sub>vj</sub> = 150 °C; 8,310 ms	365	A²s
$V_{F}$	T <sub>vi</sub> = 25 °C; I <sub>F</sub> = 25 A	max. 1,25	V
V <sub>(TO)</sub>	T <sub>vj</sub> = 150 °C	max. 0,8	V
r <sub>T</sub>	T <sub>vi</sub> = 150 °C	max. 13	mΩ
$I_{RD}$	$T_{vj} = 150 \text{ °C}; V_{DD} = V_{DRM}; V_{RD} = V_{RRM}$	max. 4	mA
			mA
R <sub>th(j-s)</sub>	per diode	2,15	K/W
tilg-3)	per module	0,36	K/W
T <sub>solder</sub>	terminals, 10s	260	°C
T <sub>vi</sub>		-40+150	°C
T <sub>stg</sub>		-40+125	°C
V <sub>isol</sub>	a. c. 50 Hz; r.m.s.; 1 s / 1 min.	3000 ( 2500 )	V
M <sub>s</sub>	mounting torque to heatsink	2	Nm
Mt			
m	approx. weight	19	g
Case	SEMITOP® 2	T 7	



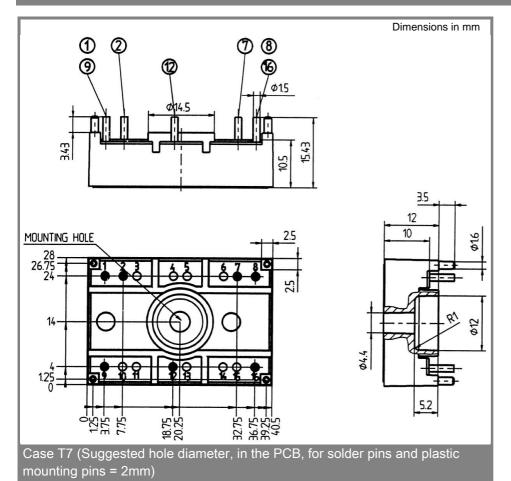
# SK 55 D

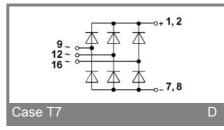






# SK 55 D





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